

TH 211-2

Non Silicone Gap Filler

Description

TH 211-2 is a yellowish, highly filled non-silicone system suitable for thermal dissipation of electronic devices. It has stable pot life and long shelf life even at room temperature of 25°C.

Applications

Heat dissipation from electronic components.

Guidelines for Use

1. Wear rubber gloves when handling the product.
2. Pick up the product from the container using hand.
3. Place the product onto the required electronic part and circuit.
4. No heating nor curing is required.
5. The product can be applied and removed easily. Care must be taken during installation to avoid tearing.

Properties

Property	Test Method	Unit	Typical Value
Chemical type	-	-	Non-silicone
Appearance	Pen 10	-	Yellowish White
Surface tack	-	-	Non tacky
Shelf life, 25°C	Pen 26	Month	12
Operating temperature	Pen 92	°C	-40 to 125
Tensile strength	PEN 92	kg/cm ²	4.0 – 6.0
Elongation	PEN 92	%	> 80
Hardness	Pen 29	Shore 00	50
Viscosity	Pen 44	cP	Pad
Thermal conductivity	ASTM D5470	Wm ⁻¹ K ⁻¹	1.4
Density	Pen 14	g/cm ³	1.5

Storage

Store this non-silicone gap filler in an air tight container in a cool (20°C to 30°C) and dark place to prolong shelf life. Avoid contact with moisture.

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Packaging & Dimension

- Sheet form
- Will provide customized dimension if required

Contact Information

Penchem Technologies Sdn Bhd
(767120-A), 1015, Jalan Perindustrian Bukit Minyak 7, 14100 Penang, Malaysia
T: +604-501 5976, 77, 78, 79
E: enquiry@penchem.com
W: www.penchem.com

Revision 6:11-Jul-18.NN